

Sub C 1.
--32. A polishing pad assembly for polishing a semiconductor wafer comprising:
a belt forming a closed loop; and
at least one polishing pad mounted on the belt.--

--33. The polishing pad assembly of Claim 32 in which said belt is formed of metal.--


Sub C 2
--34. A polishing pad assembly for polishing a semiconductor wafer comprising:
a first roller;
at least one additional roller;
a belt forming a closed loop, which belt is mounted on said first roller and
said at least one additional roller;
at least one polishing pad mounted to said belt; and
a drive system coupled to at least said first roller to rotate said first roller
and to cause said belt and said polishing pad to move in a path.--

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--35. The polishing pad assembly of Claim 34 in which said belt is formed of metal.--

REMARKS

New Claims 32-35 correspond to Claims 32-35 as added by amendment in Application Serial No. 08/2087,658 prior to the restriction requirement in that application.

Respectfully submitted,



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